Type	-	#	Hits	Search Text	DBs	Time Stamp Comments		Error Definition	rs
BRS		1	1662	screw and chip and case and substrate	ن ا	2001/02/14 13:48			0
BRS		L2	193	Ll and (clip or pawls or claw or prong)	L L	2001/02/14 11:25			0
BRS		L3	849	L1 and (clip or pawls or claw or prong or (spring adj connector) or spring)	ا ب	2001/02/14			0
BRS		Γď	196	Ll and (clip or pawls or claw or prong or (spring adj connector))	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 14:03			0
BRS		1.5	143	L1 and (clip or pawls)	USPAT; EPO; JPO; Derwent ; IBM	USPAT; EPO; JPO; JPO; Derwent 12:04 ; IBM TDB			0
BRS		1.6	38	L1 and pawls	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14	•		0
BRS		1.7	1232	screw and chip and (housing or package)and substrate	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 12:08			0
BRS		F 7	674	L7 and (clip or finger or pawls oclaw or prong or (spring adj connector) or spring)	USPAT; cr EPO; DPO; Derwent ; IBM	2001/02/14			0
BRS		F3	144	<pre>(wire adj bond) and (chip near substrate)and (cap or cover or (control adj substrate))</pre>	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14			0

Type	#	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Erro
BRS	i _	24	L9 and (removable or detachable)	1 11	2001/02/14 12:50			0
BRS	L11	140	19 and (case or hous\$ or package or plate)	u	2001/02/14 12:58		Truncation Overflow. Return string from Server is: \$`2265060	-1
BRS	112	852	power adj chip	L.	2001/02/14 12:58			0
BRS	113	П	L12 and (control adj substrate)	L)	2001/02/14 13:13			0
BRS	L14	3144	control adj substrate	עו	2001/02/14 13:02			0
BRS	115	16	L14 and (wire adj bond)	ا رر ا	2001/02/14 13:04			0
BRS	116	861	257/718.ccls.	נו	2001/02/14 13:06			0
BRS	L17	162	257/500.ccls.		2001/02/14			0
BRS	L18	0	L17 and screw	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14			0

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Error Definition									
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Time Stamp	2001/02/14 13:14	2001/02/14 13:17	2001/02/14 13:22	2001/02/14 13:25	2001/02/14 13:25	2001/02/14	2001/02/14 13:34	2001/02/14 13:35	2001/02/14 13:37
DBs	ند ا	ц	LI LI	ע	נו		ب	ч	USPAT; EPO; JPO; Derwent ; IBM
Search Text	257/678.ccls.	L19 and (wire adj bond)	L19 and screw	L19 and pawl	257/719.ccls.	257/719.ccls. and chip	257/686.ccls.	257/698.ccls.	L26 and chip and (wire adj bond)
Hits		28	38	Е	508	228	679	753	50
#	L19	L20	L21	L22	123	1.24	1.25	126	L27
Type		BRS	BRS	BRS	BRS	BRS	BRS	BRS	BRS
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"	Type	# 1	Hits	Search Text	DBs	Time Stamp (Comments	Error Definition	rs
BRS		L28	46	L25 and chip and (wire adj bond)	ا ب	2001/02/14			0
BRS	rv.	L29	2	257/688.ccls. and chip and (wire adj bond)	ادر	2001/02/14			0
BRS	S	L30	75	257/688.ccls. and chip	t t	2001/02/14			0
BRS	S	L31	307	257/696.ccls. and chip	4	2001/02/14 13:47			0
BRS	Ş	L32	367	screw and chip and case and substrate and (removable or detachable)	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 13:56			0
BRS	S	L33	8163	(case or housing or packade) near (removable or detachable)	USPAT; EPO; JPO; Derwent ; IBM	2001/02/14 13:58			0
BB H	BRS	L34	П	on adj board adj (semiconductor or chip)	USPAT; EPO; or JPO; Derwent ; IBM TDB	2001/02/14 13:59			0
<u> </u>	BRS	L35	1595	(clip or pawls or claw or prong or (spring adj connector)) near (electrodes or terminal or lead)		2001/02/14 14:06			0
В	BRS	136	΄ α	L35 and (wire adj bond)	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 14:07			

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37-								
7 BRS	L37	152	L35 and chip	USFAL; EPO; JPO; Derwent ; IBM TDB	EPO; EPO; JPO; Derwent 14:08 ; IBM TDB			0

1770 1810	Γ			+ = < E - 1 = = < C	DBs	Time Stamp	Comments	Error Definition
BINES 380 257/341.ccls. 1057/12 BINT 1057		Type	Hits	Seatch		١.		
BRS 466 257/241.cc1s. and pauls BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/241.cc1s. and pauls BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/241.cc1s. and plate BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/241.cc1s. and plate BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/27.cc1s. and plate BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/27.cc1s. and control add substrate) BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/27.cc1s. and control add substrate) BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/27.cc1s. and control add substrates BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/27.cc1s. and control add substrates BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/27.cc1s. and control add substrates BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/27.cc1s. and delip BRYTISE DEPARTMENT 2001/02/13 BRS 0 257/27.cc1s. and delip 2007/02/13 BRS 0 257/27.cc1s. and delip 2007/02		BRS	380	257/341.ccls.	. DDO: TDO: Derivent:			
Bigging Bigg	2	BRS	466	257/341.ccls.	DB	,		
Bits 0 277/241.ccls. and (power add clipp) UBYPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 334 257/241.ccls. and plate USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and (control add substrate) USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and (control add substrate) USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and (control add substrate) USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and (control add substrate) USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and (control add substrate) USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and (control add substrate) USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and (lCBT or Mosfet or mos or 18 MTDB Bits 0 257/271.ccls. and 257/35.ccls. USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and 257/35.ccls. USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip USPAT; EPO; JPO; Derewelt; 2001/02/13 Bits 0 257/271.ccls. and chip	_ m	BRS	0	and.	EPO; JPO; Derwent; B	18		
Bits	4	BRS	0	. and (power adj	EPO; JPO; Derwent; B			
BKS S54 S57/727.cc18. and (on adj board) IBM TDB IBM TDB	5	BRS	83	. and	EPO; JPO; Derwent;			
Biss O 21/721.ccls. and (on adj board) IBM TOB	9	BRS	554	257/727.ccls.	EPO; JPO; Derwent; 3	;		
BRS 0 27/721.ccls. and (control ad) substrate) IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 0 27/721.ccls. and (control ad) substrate) IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 137 25/727.ccls. and (IGBT or Mosfet or mos or IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 24 25/727.ccls. and (IGBT or Mosfet or mos or IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 2 25/727.ccls. and 25/735.ccls. IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 2 25/727.ccls. and 25/735.ccls. IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 2 25/727.ccls. and chip and substrate IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 2 25/727.ccls. and chip and substrate IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 2 25/727.ccls. and chip and substrate IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 2 25/727.ccls. and chip and substrate IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 1039 25/727.ccls. and chip and substrate IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 1039 25/723.ccls. IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 1039 25/723.ccls. IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 2 25/723.ccls. and chip and case IBRNT; EPO; POP, Derwent; 2001/02/13 BRS 2 25/723.ccls. and chip and case IBRNT; EPO; JPO; Derwent; 2001/02/13 BRS 2 25/723.ccls. and chip and power IBRNT; EPO; JPO; Derwent; 2001/02/13 BRS 2 25/723.ccls. and chip and power 1BRNT; EPO; JPO; Derwent; 2001/02/13 BRS 2 25/723.ccls. and chip 1BRNT; EPO; JPO; Derwent; 2001/02/13 BRS 2 25/723.ccls. and chip and power 1BRNT; EPO; JPO; Derwent; 2001/02/13 BRS 2 25/723.ccls. and chip and power 1BRNT; EPO; JPO; Derwent; 2001/02/13 BRS 2 25/723.ccls. and chip and power 1BRNT; EPO; JPO; Derwent; 2001/02/13 BRS 2 25/723.ccls. and chip and power 1BRNT; EPO; JPO; Derwent; 2001/02/13 BRS 2 2 2 2 2 2 2 2 2	1	BRS	0	. and (on adj	JPO; Derwent;	1		
BRS 0 277/72.ccls. and (control ad) substrate) USBAT; EPO; JPO; Derwent; JON 20/10/21/3 BRS 137 257/72.ccls. and (1GBT or MOsfet or mos or ISMT; EPO; JPO; Derwent; JON 20/10/21/3 LBM TDB CONTROL 20/10/21/3 BRS 54 (257/72.ccls. and 257/735.ccls. and 257/735.ccls. and 257/735.ccls. and 257/735.ccls. and 257/735.ccls. ISMT; EPO; JPO; Derwent; JON 20/10/21/3 20/10/21/3 BRS 2 257/72.ccls. and 257/735.ccls. ISMT; EPO; JPO; Derwent; JON 20/10/21/3 20/10/21/3 BRS 149 257/72.ccls. and chip and substrate USPMT; EPO; JPO; Derwent; JON 20/10/21/3 15M TDB 20/10/21/3 BRS 319 257/72.ccls. and chip and substrate USPMT; EPO; JPO; Derwent; JON 20/10/21/3 15M TDB 20/10/21/3 BRS 319 257/72.ccls. and spring USPMT; EPO; JPO; Derwent; JON 20/10/21/3 20/10/21/3 BRS 319 257/72.ccls. and chip and substrate USPMT; EPO; JPO; Derwent; JON 20/10/21/3 USPMT; EPO; JPO; Derwent; JON 20/10/21/3 BRS 1063 257/72.ccls. and chip and case USPMT; EPO; JPO; Derwent; JON 20/10/21/3 USPMT; EPO; JPO; Derwent; JON 20/10/21/3 BRS 500 257/724.ccls. and chip and case USPMT; EPO; JPO; Derwent; JON 20/10/21/3 USPMT; EPO; JPO; Derwent; J	ω	BRS	0	and (ocntrol adj su	JPO; Derwent;	1		
BRS 137 257/727.ccls. and (IGBT or Mosfet or mos or 18M TDB USRATE BOOK JPO, Derwert; 2001/02/13 C001/02/13 BRS 64 (257/727.ccls. and GIAD or Mosfet or mos or 18M TDB USRATE BOO, JPO, Derwert; 2001/02/13 C001/02/13 BRS 0 257/727.ccls. and 257/735.ccls. USRATE BOO, JPO, Derwert; 2001/02/13 C001/02/13 BRS 149 257/727.ccls. and chip and substrate 18M TDB USRATE BOO, JPO, Derwert; 2001/02/13 C001/02/13 BRS 130 257/727.ccls. and chip and substrate 18M TDB USRATE BOO, JPO, Derwert; 2001/02/13 C001/02/13 BRS 132 257/727.ccls. and spring 18M TDB USRATE BOO, JPO, Derwert; 2001/02/13 C001/02/13 BRS 1063 257/727.ccls. and chip and case 18M TDB USRATE BOO, JPO, Derwert; 2001/02/13 C001/02/13 BRS 1063 257/723.ccls. and chip and case 18M TDB USRATE BOO, JPO, Derwert; 2001/02/13 C001/02/13 BRS 607 257/723.ccls. and chip and case 18M TDB USRATE BOO, JPO, Derwert; 2001/02/13 C001/02/13 BRS 500 257/723.ccls. and chip and case 18M TDB USRATE BOO, JPO, Derwert; 2001/02/13 BRS 60	6	BRS	0	and (control adj su	EPO; JPO;	18:2	4.000	
BRS 54 (257/727.cc1s. and clbf) and chbf or Mosfet or mos or lym tob USRATA FROM JOD Derwent; and clbf or Mosfet or mos or lym tob USRATA FROM JOD Derwent; and clbf or Mosfet or mos or lym tob 18M TOB 257/727.cc1s. and 257/735.cc1s. USRATA FROM JOD Derwent; and clbf or Mosfet or mos or lym tob 18M TOB 257/727.cc1s. and chbp and substrate USRATA ERO; JPO; Derwent; and clbf or Mosfet or lym tob 257/727.cc1s. and chbp and substrate 18M TOB 257/727.cc1s. 257/727.cc1s. and chbp and substrate 18M TOB 257/727.cc1s. 257/727.cc1s. and chbp and substrate 18M TOB 257/727.cc1s.	10	BRS	137	and (IGBT or MOsfet or mos	EPO; JPO;	18:4		
BRS 0 257/72.ccls. and 257/735.ccls. USPAT; EPO; JPO; Derwent; Derwent of the part of th	1	BRS	54	and (IGBT or MOsfet or mosio	EPO; JPO; B			
BRS 2 257/727.ccls. and 257/735.ccls. INSPAT: EPD: JPO; Derwent;	12	BRS	0	257/72.ccls. and 257/735.ccls.	EPO; JPO;	;		
BRS 149 257/727.ccls. and chip USRAT; EPO; JPO; Derwent; DIAD TOB 2001/02/13 BRS 83 257/727.ccls. and chip and substrate USRAT; EPO; JPO; Derwent; DIAD TOB 2001/02/13 BRS 212 257/727.ccls. and spring USRAT; EPO; JPO; Derwent; DOI	13	BRS	2	and	JPO;	;		
BRS 33 257/727.ccls. and chip and substrate USPAT; EPO; JPO; Derwent; DO1/02/13 201/02/13 BRS 212 257/727.ccls. and spring USPAT; EPO; JPO; Derwent; DO1/02/13 2001/02/13 BRS 139 257/727.ccls. USPAT; EPO; JPO; Derwent; DO1/02/13 2001/02/13 BRS 1063 257/724.ccls. USPAT; EPO; JPO; Derwent; DO1/02/13 2001/02/13 BRS 1080 257/723.ccls. USPAT; EPO; JPO; Derwent; DO1/02/13 2001/02/13 BRS 1039 257/723.ccls. and chip and case USPAT; EPO; JPO; Derwent; DO1/02/13 2001/02/13 BRS 570 257/724.ccls. and chip and case USPAT; EPO; JPO; Derwent; DO1/02/13 2001/02/13 BRS 570 257/724.ccls. and chip and power USPAT; EPO; JPO; Derwent; DO1/02/13 2001/02/13 BRS 570 257/724.ccls. and chip and power USPAT; EPO; JPO; Derwent; DO1/02/13 2001/02/13 BRS 633 257/724.ccls. and chip and power USPAT; EPO; JPO; Derwent; DO1/02/13 2001/02/13 BRS 633 257/724.ccls. and chip and power USPAT; EPO; JPO; Derwent; DO1/02/13 2001/02/13	1.4	BRS	149	and.	USPAT; EPO; JPO; Derwent; IBM TDB	18		
BRS 12 257/727.ccls. and spring USPAT; EPO; JPO; Derwent; Derwent 201/02/13 BRS 319 257/735.ccls. USPAT; EPO; JPO; Derwent; Derwent	15	BRS	83	and chip and	USPAT; EPO; JPO; Derwent; IBM TDB			
BRS 199 257/735.cc1s. USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS 1063 257/724.cc1s. USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS 618 257/72.cc1s. USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS 657 257/723.cc1s. and chip and case USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS 667 257/724.cc1s. and chip and case USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS 570 257/724.cc1s. and chip and case USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS 570 257/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS 67 257/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS 63 257/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS 63 257/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS 63 257/701.cc1s. USPAT; EPO; JPO; Derwent; DERWENT 2001/02/13 BRS	19	-	212	and	JPO;			
BRS 1063 257/724.cc1s. USPAT; EPO; JPO; Derwent; Derwen	17		319	257/735.ccls.	JPO;			
BRS 618 257/72.cc1s. USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 1039 257/723.cc1s. and chip USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 667 257/723.cc1s. and chip) and case USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 570 257/724.cc1s. and chip and case USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 570 257/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 570 257/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 63 257/691.cc1s. IBM TDB USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 63 257/691.cc1s. IBM TDB 2001/02/13 2001/02/13 BRS 63 257/691.cc1s. IBM TDB 2001/02/13 2001/02/13 BRS 409 257/701.cc1s. IBM TDB 1BM TDB 2001/02/14 BRS 737 257/734.cc1s. 1BM TDB 1BM TDB 2001/02/14	18		1063	257/724.ccls.	JPO;			
BRS 1039 257/723.cc1s. and chip USPAT; EPO; JPO; Derwent; 2001/02/13 BRS 667 257/723.cc1s. and chip) and case USPAT; EPO; JPO; Derwent; 2001/02/13 BRS 303 (257/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; 2001/02/13 BRS 277 257/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; 2001/02/13 BRS 27 257/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; 2001/02/13 BRS 0 257/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; 2001/02/13 BRS 0 257/724.cc1s. ERO USPAT; EPO; JPO; Derwent; 2001/02/13 BRS 409 257/707.cc1s. USPAT; EPO; JPO; Derwent; 2001/02/13 BRS 409 257/734.cc1s. USPAT; EPO; JPO; Derwent; 2001/02/13 BRS 409 257/734.cc1s. USPAT; EPO; JPO; Derwent; 2001/02/14 BRS 409 257/734.cc1s. USPAT; EPO; JPO; Derwent; 2001/02/14	19	\neg	618	257/72.ccls.	EPO;	П		
BRS 667 257/723.ccls. and chip uSPAT; EPO; JPO; Derwent; JBM TDB 2001/02/13 BRS 303 (257/723.ccls. and chip) and case USPAT; EPO; JPO; Derwent; JBM TDB 2001/02/13 BRS 570 257/724.ccls. and chip and power USPAT; EPO; JPO; Derwent; JBM TDB 2001/02/13 BRS 271 257/724.ccls. and chip and power USPAT; EPO; JPO; Derwent; JBM TDB 2001/02/13 BRS 0 257/691.ccls. USPAT; EPO; JPO; Derwent; JBM TDB 2001/02/13 BRS 633 257/691.ccls. LBM TDB 2001/02/13 BRS 409 257/707.ccls. LBM TDB 2001/02/13 BRS 137 257/734.ccls. LBM TDB 2001/02/13 BRS 138 257/734.ccls. LBM TDB 2001/02/13	20		1039	257/723.ccls.	EPO; JPO; B			
BRS 303 (257/723.ccls. and chip) and case USPAT; EPO; JPO; Derwent; Derwe	21	(667	and	EPO; JPO;	2001/02/13		
BRS 570 257/724.ccls. and chip USPAT; EPO; JPO; Derwent; Derwent	22		303	and chip) and	JPO;	2001/02/13	,	
BRS 271 257/724.ccls. and chip and power USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 0 257/691.ccls USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 633 257/691.ccls. USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 409 257/707.ccls. USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/13 BRS 737 257/734.ccls. USPAT; EPO; JPO; Derwent; IBM TDB 2001/02/14	23		570	and	JPO;	2001/02/13		
BRS 0 257/691.ccls USPAT; EPO; JPO; Derwent; ISO1/02/13 2001/02/13 BRS 633 257/691.ccls. 1BM TDB 2001/02/13 BRS 409 257/707.ccls. 1BM TDB 2001/02/13 BRS 737 257/734.ccls. 1BM TDB 2001/02/14	24	-	271	and chip and	EPO; JPO;	2001/02/13		
BRS 633 257/691.ccls. USPAT; EPO; JPO; Derwent; 2001/02/13 2001/02/13 BRS 409 257/707.ccls. IBM TDB 2001/02/13 BRS 737 257/734.ccls. IBM TDB 2001/02/14	25		0	257/691.ccls	JPO;	2001/02/13		
BRS 409 257/707.ccls. IBM TDB 2001/02/13 BRS 737 257/734.ccls. IBM TDB 2001/02/14	26		633	257/691.ccls.	JPO;	2001/02/13		
BRS 737 257/734.ccls. USPAT; EPO; JPO; Derwent; 2001/02/14	27		409	257/707.ccls.	EPO;	2001/02/13		
	28	1	737	257/734.ccls.	EPO;	2001/02/14		

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1	Type	#	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Erro
1		LT.	0	("chip and pawl").PN.	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 18:29			0
; ш	BRS	L2	752	chip and pawl	L+	2001/02/14 18:33			0
1 144	BRS	L3	173	chip and pawl and substrate		2001/02/14			0
	BRS	1.4	27667	(case or housing or package) and pawl	ע	2001/02/14 18:43			С
	BRS	L5	593	L4 and chip		2001/02/14 18:44		·	0
	BRS	7.6	1	L2 and (wire adj bond)	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 19:01			0
	BRS	17	152	screw and (wire adj bond)and chip	USPAT; EPO; JPO; Derwent ; IBM	2001/02/14 19:04			0
	BRS	81	11829	screw and chip	USPAT; EPO; JPO; Derwent ; IBM	2001/02/14 19:05			0
I .	BRS	F 6 7	36	screw and chip and (control near(substrate or (ciruit adj board)))	USPAT; EPO; JPO; Derwent ; IBM TDB				0
10	BRS	L10			USPAT	2001/02/14 19:10			0
11	BRS	111	Π		USPAT	2001/02/14 19:10			0

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	Type	#	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	rs
12	BRS	L12	1		USPAT	2001/02/14 19:10			0
13	BRS	L13	1		USPAT	2001/02/14 19:11			0
14	BRS	L14	5244	power and chip and screw	_ t	2001/02/14			0
15	BRS	115	54	L14 and (screw near (case or wall or board))	<u>.</u>	2001/02/14 19:51			0
16	BRS	177	320	L16 and chip	USPAT; EPO; JPO; Derwent ; IBM	2001/02/14 19:55			0
17	BRS	118	3	L17 and (wire adj bond)	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14			0
18	BRS	119	34	L17 and (screw or pawl)	μ	2001/02/14 20:00			0
1 9	BRS	L20	109	Igbt and screw	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14			0